

**AMENDMENTS TO THE CLAIMS:**

*Please amend the claims as follows:*

1. (Currently amended) An electronic component comprising:  
a conductive pattern comprising at least two electrodes provided on an insulating substrate;  
a metal film formed by a plating method on a surface of the conductive pattern; and  
a metal oxide layer formed by oxidizing the metal film and disposed on the surface of the conductive pattern,  
wherein the metal oxide layer is formed on a portion of the substrate between electrodes of the conductive pattern on the substrate,  
the conductive pattern uses an electrode material including at least Ag,  
the metal oxide layer includes one material selected from the group consisting of NiO, ZnO, and CuO, and  
the metal oxide layer has a thickness ranging from 0.5 $\mu$ m to 5 $\mu$ m.
2. (Cancelled)
3. (Previously presented) The electronic component as defined in claim 1, wherein the metal film is formed by a plating method on a surface of the substrate, where the conductive pattern is provided.
4. (Previously presented) The electronic component as defined in claim 1, wherein the substrate uses a ceramic substrate.
5. (Previously presented) The electronic component as defined in claim 1, wherein the substrate uses a glass-ceramic substrate.

6. (Previously presented) The electronic component as defined in claim 1, wherein the substrate uses an organic substrate.

7. (Cancelled)

8. (Original) The electronic component of claim [[7]] 1, wherein the electrode material includes one material selected from the group consisting of Ag, Ag – Pt, and Ag – Pd.

9-11. (Cancelled)

12. (Previously presented) The electronic component as defined in claim 1, wherein a part of the conductive pattern is exposed at the surface of the component.

13. (Cancelled)

14. (Previously presented) The electronic component as defined in claim 3, wherein a part of the conductive pattern and a part of the substrate are exposed at the surface of the component.

15. (Withdrawn – currently amended) A method of manufacturing an electronic component, the method comprising the steps of:

forming a conductive pattern on a surface of an insulating substrate;

forming a metal film by a plating method on a surface of the conductive pattern and on a portion of the surface of the insulating substrate; and

forming a metal oxide layer by oxidizing the metal film on the surface of the conductive pattern and on the portion of the surface of the insulating substrate,

wherein the conductive pattern uses electrode material including at least Ag,

the metal oxide layer includes one material selected from the group consisting of NiO,

ZnO, and CuO, and

the metal oxide layer has a thickness ranging from 0.5 $\mu$ m to 5 $\mu$ m.

16-17. (Cancelled)

18. (Withdrawn) The method as defined in one of claim 15, wherein the plating method uses an electroless plating method.

19. (Withdrawn) The method as defined in claim 15 wherein the oxidizing is done by a heat treatment.

20. (Withdrawn) The method as defined in claim 19, wherein the heat treatment is carried out at a temperature not higher than a melting point of the conductive pattern.

21. (Withdrawn) The method of manufacturing an electronic component according to claim 15, wherein the metal film is a nickel film, and

said step of forming the metal oxide layer comprises forming a nickel oxide layer as the metal oxide layer at least on the surface of the conductive pattern by providing the nickel film with an oxidation heat treatment at a temperature between 850°C and a melting point of electrode material forming the conductive pattern.